RM0041 Revision history

28 Revision history

Table 161. Document revision history

lable 161. Document revision history				
Date	Revision	Changes		
26-Feb-2010	1	Initial release.		
04-Jun-2010	2	Corrected description of TIMx_CCER register in Section 12.4.9 on page 272 and Section 13.4.9 on page 334 Updated Section 14.3.5: Input capture mode on page 353 Added method 1 and 2 in Section 22.3.3: I2C master mode Updated note in POS bit description Section 22.6: I ² C registers		
12-Oct-2010	3	Updated for high density value line devices Updated Section 20.5.2: Supported memories and transactions Added Section 14: General-purpose timers (TIM12/13/14) Added Section 20: Flexible static memory controller (FSMC)		
21-Jul-2011	4	Corrected Figure 2: High density value line system architecture on page 35 Updated SPI table in Section 7.1.11: GPIO configurations for device peripherals on page 109 Updated bit descriptions in Section 7.3.1: Clock control register (RCC_CR) on page 99 and Section 8.3.1: Clock control register (RCC_CR) on page 132 EXTI: Updated Figure 18: External interrupt/event controller block diagram ADC: Corrected Table 59: External trigger for regular channels for ADC1 and Table 60: External trigger for injected channels for ADC1 on page 171 TIMERS: Removed wrong references to 32-bit counter in Section 13.4: TIMx2 to TIM5 registers on page 321 TIM1&TIM8: Updated example and definition of DBL bits in Section 12.4.19: TIM1 DMA control register (TIMx_DCR). Added example related to DMA burst feature and description of DMAB bits in Section 12.4.20: TIM1 DMA address for full transfer (TIMx_DMAR). TIM2 to TIM5 and TIM15 to 17: added example and updated definition of DBL bits in Section 13.4.18: TIMx DMA control register (TIMx_DCR). Added example related to DMA burst feature and description of DMAB bits in Section 13.4.18: TIMx DMA address for full transfer (TIMx_DCR). Updated definition of DBL bits in Section 13.4.17: TIMx DMA control register (TIMx_DCR). In Section 12.3.3: Repetition counter Added paragraph "In Center aligned mode, for odd values of RCR," Modified Figure 167: Update rate examples depending on mode and TIMx_RCR register settings on page 398. WWDG Updated Section 19.2: WWDG main features. Updated Section 19.3: WWDG functional description to remove paragraph related to counter reload using EWI interrupt.		



RM0041 Rev 6 703/709

Revision history RM0041

Table 161. Document revision history (continued)

Date	Revision	Changes	
21-Jul-2011	4 continued	Updated BERR bit description in Section 22.6.6: I ² C Status register 1 (I2C_SR1). Updated Note: in Section 22.6.8: I ² C Clock control register (I2C_CCR). Added note 3 below Figure 235: Transfer sequence diagram for slave transmitter on page 570. Added note below Figure 236: Transfer sequence diagram for slave receiver on page 571. Modified Section: Closing slave communication on page 571. Modified STOPF, ADDR, bit description in Section 22.6.6: I ² C Status register 1 (I2C_SR1) on page 591. Modified Section 22.6.7: I ² C Status register 2 (I2C_SR2). USART: Updated Figure 251: Mute mode using address mark detection for Address = 1.SPI: Modified Slave select (NSS) pin management on page 539 and note on NSS in Section 21.3.3: Configuring the SPI in master mode FSMC: Updated description of DATLAT, DATAST, and ADDSET bits in SRAM/NOR-Flash chip-select timing registers 14 (FSMC_BTR14). Updated byte select description in Section 20.5.2: Supported memories and transactions on page 501	
10-Jun-2016	5	Added SCL master clock generation and Note: to Entering Stop mode. Added Table 88: Minimum and maximum timeout values @24 MHz (f _{PCLK1}). Updated Table 74: TIMx Internal trigger connection, Table 79: TIMx Internal trigger connection, Table 92: Programmable NOR/PSRAM access parameters, Table 97: NOR flash/PSRAM controller: example of supported memories and transactions and Table 114: FSMC_BCRx bit fields. Updated Figure 5: Power on reset/power down reset waveform, Figure 6: PVD thresholds, Figure 7: Simplified diagram of the reset circuit, Figure 40: Advanced-control timer block diagram, Figure 68: Output stage of capture/compare channel (channel 1 to 3), Figure 78: Clearing TIMx OCxREF, Figure 121: Clearing TIMx OCxREF, Figure 128: Master/Slave timer example, Figure 158: TIM16 and TIM17 block diagram, Figure 173: Output stage of capture/compare channel (channel 1), Figure 200: Watchdog block diagram, Figure 201: Window watchdog timing diagram, Figure 202: FSMC block diagram, Figure 217: Asynchronous wait during a read access, Figure 218: Asynchronous wait during a write access and Figure 220: Synchronous multiplexed read mode - NOR, PSRAM (CRAM). Updated caption of Figure 101: Counter timing diagram, Update event and of Figure 208: Mode2 and mode B read accesses.	

RM0041 Revision history

Table 161. Document revision history (continued)

Date Re	evision	e 161. Document revision history (continued) Changes
10lun-2016	5 ntinued	,

Revision history RM0041

Table 161. Document revision history (continued)

Date	Revision	Changes
10-Jun-2016	5 continued	Updated: - Mode 1 - SRAM/PSRAM (CRAM), Asynchronous static memories (NOR flash memory, PSRAM, SRAM), Mode 2/B - NOR flash, SRAM/NOR-Flash chip-select timing registers 14 (FSMC_BTR14), SRAM/NOR-Flash write timing registers 14 (FSMC_BWTR14), SRAM/NOR-flash chip-select control registers 14 (FSMC_BCR14), Section 20.5.4: NOR flash/PSRAM controller asynchronous transactions and Section 20.5.6: NOR/PSRAM control registers. Replaced M/SL with MSL throughout Section 22: Inter-integrated circuit (I2C) interface, and updated Section 22.6.1: I²C Control register 1 (I2C_CR1), Section 22.6.2: I²C Control register 2 (I2C_CR2) and Section 22.6.9: I²C TRISE register (I2C_TRISE). Replaced nCTS with CTS, nRTS with RTS and SCLK with CK throughout Section 27: Universal synchronous asynchronous receiver transmitter (USART). Updated: - Section 27.3.8: LIN (local interconnection network) mode, Selecting the
		proper oversampling method, How to derive USARTDIV from USART_BRR register values when OVER8=0 and How to derive USARTDIV from USART_BRR register values when OVER8=1 and Section 27.6.6: Control register 3 (USART_CR3).
12-Dec-2022	6	Updated Introduction, Section 4.4.1: Power control register (PWR_CR), Section 5.2: BKP main features, Section 5.4: BKP registers, Section 12.3.21: Debug mode, Section 12.4.7: TIM1 capture/compare mode register 1 (TIMx_CCMR1), Section 12.4.14: TIM1 capture/compare register 1 (TIMx_CCR1), Section 12.4.17: TIM1 capture/compare register 4 (TIMx_CCR4), Section 12.4.20: TIM1 DMA address for full transfer (TIMx_DMAR), Section 13.4.7: TIMx capture/compare mode register 1 (TIMx_CCMR1), sections 13.4.13 to 13.4.16, Section 14.4.7: TIM capture/compare mode register 1 (TIMx_CCMR1), sections 14.4.11 to 14.4.13, Section 14.5.9: TIM13/14 auto-reload register (TIMx_ARR), Section 14.5.10: TIM13/14 capture/compare register 1 (TIMx_CCR1), Section 15.5.5: TIM15 status register (TIM15_SR), Section 15.6.12: TIM16&TIM17 capture/compare register 1 (TIMx_CCR1), and Section 19.4: How to program the watchdog timeout. Added Section 1.4: General information and Section 27: Important security notice. Updated Table 14: BKP register map and reset values and Table 69: TIM1 register map and reset values. Updated Figure 6: PVD thresholds, Figure 40: Advanced-control timer block diagram, Figure 134: General-purpose timer block diagram (TIM12), and Figure 259: Parity error detection using the 1.5 stop bits. Minor text edits across the whole document.

Index RM0041

Index

Α	DAC_DHR12R1	
ADC CR1176	DAC_DHR12R2	
ADC CR2	DAC_DHR12RD	
ADC_DR187	DAC_DHR8R1	
ADC HTR182	DAC_DHR8R2	
-	DAC_DHR8RD	209
ADC_JDRx	DAC_DOR1	209
ADC_JOFRx181	DAC_DOR2	209
ADC_JSQR186	DAC_SR	
ADC_LTR	DAC_SWTRIGR	
ADC_SMPR1	DBGMCU_CR	
ADC_SMPR2	DBGMCU_IDCODE	
ADC_SQR1183	DMA_CCRx	
ADC_SQR2184	DMA_CMARx	
ADC_SQR3185	DMA_CNDTRx	
ADC_SR	DMA_CPARx	
AFIO_EVCR	DMA_IFCR	
AFIO_EXTICR1126	DMA_ISR	
AFIO_EXTICR2126		
AFIO_EXTICR3127	F	
AFIO_EXTICR4127	E	
AFIO_MAPR124	EXTI_EMR	140
AFIO_MAPR2128	EXTI FTSR	141
	EXTI IMR	140
В	EXTI_PR	142
	EXTI_RTSR	
BKP_CR	EXTI_SWIER	
BKP_CSR	_	
BKP_DRx	г	
BKP_RTCCR66	F	
	FSMC_BCR14	526
C	FSMC_BTR14	529
CEC CFGR663	FSMC_BWTR14	532
—		
CEC_CSR	G	
—		
CEC_OAR	GPIOx_BRR	
CEC_PRES	GPIOx_BSRR	
CEC_RXD	GPIOx_CRH	
CEC_TXD	GPIOx_CRL	
CRC_DR	GPIOx_IDR	
CRC_IDR48	GPIOx_LCKR	
	GPIOx_ODR	115
D		
DAC_CR202	1	
DAC_DHR12L1		
	I2C_CCR	
DAC_DHR12LD	I2C_CR1	
DAC_DHR12LD208	I2C_CR2	588

\7/

RM0041 Index

I2C_DR591	TIM15_BDTR431
I2C_OAR1590	TIM15_CCER426
I2C_OAR2590	TIM15_CCMR1423
I2C_SR1	TIM15_CCR1430
I2C_SR2	TIM15_CCR2431
I2C_TRISE	TIM15_CNT
IWDG_KR483	TIM15_CR1416
IWDG_PR483	TIM15_CR2417
IWDG_RLR484	TIM15_DCR433
IWDG_SR484	TIM15_DIER420
	TIM15_DMAR
P	TIM15_EGR422
	TIM15_PSC429
PWR_CR	TIM15_RCR430
PWR_CSR62	TIM15_SMCR418
	TIM15_SR421
R	TIMx_ARR336, 375, 385, 467
	TIMx_BDTR
RCC_AHBENR90	TIMx_CCER272, 334, 374, 384, 445
RCC_APB1ENR	TIMx_CCMR1268, 330, 371, 381, 443
RCC_APB1RSTR88	TIMx_CCMR2270, 333
RCC_APB2ENR	TIMx_CCR1276, 336, 376, 386, 449
RCC_APB2RSTR86	TIMx_CCR2
RCC_BDCR97	TIMx_CCR3
RCC_CFGR82	TIMx_CCR4
RCC_CFGR2100	TIMx_CNT274, 335, 375, 385, 448, 466
RCC_CIR84	TIMx_CR1257, 321, 364, 379, 437, 463
RCC_CR80	TIMx_CR2258, 323, 365, 438, 465
RCC_CSR98	TIMx_DCR 280, 338, 451
RTC_ALRH	TIMx_DIER263, 326, 367, 380, 440, 465
RTC_ALRL	TIMx_DMAR281, 338, 452
RTC_CNTH	TIMx_EGR 266, 329, 370, 381, 442, 466
RTC_CNTL	TIMx_PSC
RTC_CRH	TIMx_RCR
RTC_CRL	TIMx_SMCR261, 324, 366
RTC_DIVH	TIMx_SR265, 327, 369, 380, 441, 466
RTC_DIVE477 RTC_PRLH	
RTC_PRLL	U
KTO_FREE	
	USART_BRR
S	USART_CR1
SPI CR1559	USART_CR2
SPI_CR2560	USART_CR3
SPI_CRCPR	USART_DR
SPI_DR562	USART_GTPR645
SPI_RXCRCR563	USART_SR636
SPI_SR561	
SPI_TXCRCR564	W
5s	WWDG_CFR 492
-	WWDG_CFR
Т	WWDG_CR
TIM15_ARR	****DO_51\\492
_	

IMPORTANT NOTICE - PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved



RM0041 Rev 6 709/709